2SK3159

Silicon N Channel MOS FET High Speed Power Switching

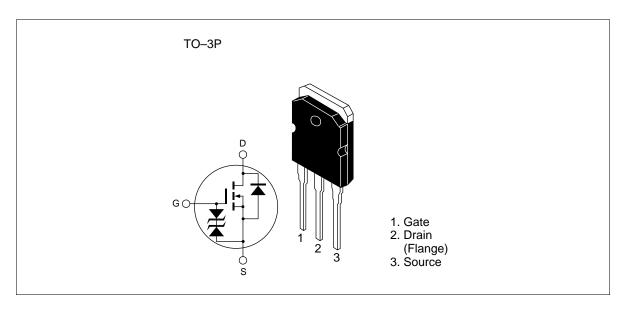
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ADE-208-774 (Z) Target Specification 1st. Edition February 1999

Features

- Low on-resistance $R_{DS} = 23 \text{ m}\Omega \text{ typ.}$
- High speed switching
- 4 V gate drive device can be driven from 5 V source

Outline





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Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	150	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	50	A
Drain peak current	Note1 D(pulse)	200	A
Body-drain diode reverse drain current	I _{DR}	50	A
Avalanche current	I _{AP} Note3	50	A
Avalanche energy	E _{AR} Note3	187	mJ
Channel dissipation	Pch Note2	125	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

- Note: 1. PW \leq 10 μ s, duty cycle \leq 1%
 - 2. Value at Tc = 25°C
 - 3. Value at Tch = 25°C, Rg \geq 50 Ω

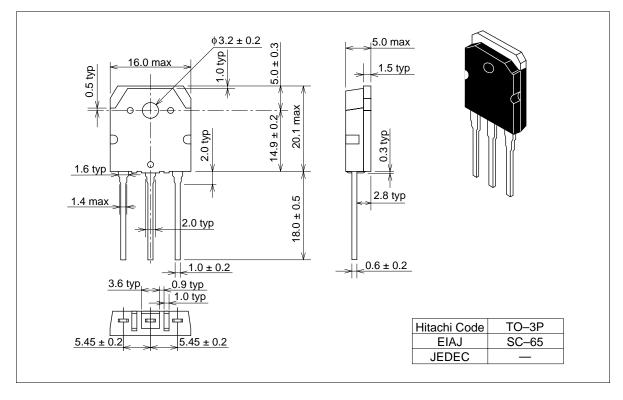
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	150	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 150 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	23	30	mΩ	$I_D = 25 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
resistance	R _{DS(on)}	_	28	48	mΩ	$I_D = 25 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	27	45	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	4000	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	1650	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	590	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	30	_	ns	I _D = 25 A, V _{GS} = 10 V
Rise time	t _r	_	280	_	ns	$R_L = 1.2 \Omega$
Turn-off delay time	t _{d(off)}	_	830	_	ns	
Fall time	t _f	_	450	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.95	_	V	$I_F = 50 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	200	_	ns	$I_F = 50 \text{ A}, V_{GS} = 0$ diF/ dt = 50 A/ μ s

Note: 4. Pulse test

Package Dimensions

Unit: mm



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